



PCB LAYOUT TOP VIEW

MATERIALS
 HOUSING: HI-TEMP. PLASTIC(LCP E130) (UL 94V-0)
 SHELL: COPPER ALLOY, NICKEL PLATING
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT
 AREA TIN PLATED ON SOLDER TAIL

SPECIFICATION
 CURRENT RATING: 0.5 AMP MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 60m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 OPERATION TEMPERATURE: -25°C+85°C

CARD DETECTION SWITCH			
WHEN CARD IS EJECTED		WHEN CARD IS INSERED	
OPEN Cd G		CLOSE Cd G	
Pin NO.	Pin assignment	Pin NO.	Pin assignment
1	DAT2	6	VSS
2	CD/DAT3	7	DAT0
3	CMD	8	DAT1
4	VDD	WP	CD
5	CLK	CD	GND

DIMENSIONS TOLERANCE METRIC Up to 5 ±0.2 Above 5~15 ±0.3 Above 15~30 ±0.4 Above 30~50 ±0.5 Angle ±0.3°	UNITS	MM	FINISH	SEE NOTE	CH'K	Calvin	DRAW NAME		WISCONN Technology Co., Ltd Tel:+886-2-2790-1979 Fax:+886-2-2790-1569						
	QTY	N/A	DRAW	Johnson	APP'D	Selena	MICRO SD NON PUSH PCB MOUNT SMT								
	MT'L	SEE NOTE	DE'N	Mike	DATE	January . 07 . 2021	PART NUMBER		WMSD-10-FRNSS1						
							DRAW NUMBER		T004						
						FILE NAME .DWG		SCALE	1/1	SIZE	A4	SHEET	1	REV.	A